

# MC14024B

## 7-Stage Ripple Counter

The MC14024B is a 7-stage ripple counter with short propagation delays and high maximum clock rates. The Reset input has standard noise immunity, however the Clock input has increased noise immunity due to Hysteresis. The output of each counter stage is buffered.

### Features

- Diode Protection on All Inputs
- Output Transitions Occur on the Falling Edge of the Clock Pulse
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4024B
- Pb-Free Packages are Available

### MAXIMUM RATINGS (Voltages Referenced to $V_{SS}$ )

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
$V_{in}, V_{out}$	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
$I_{in}, I_{out}$	Input or Output Current (DC or Transient) per Pin	$\pm 10$	mA
$P_D$	Power Dissipation, per Package (Note 1)	500	mW
$T_A$	Ambient Temperature Range	-55 to +125	$^{\circ}C$
$T_{stg}$	Storage Temperature Range	-65 to +150	$^{\circ}C$
$T_L$	Lead Temperature (8-Second Soldering)	260	$^{\circ}C$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### 1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/ $^{\circ}C$  From 65 $^{\circ}C$  To 125 $^{\circ}C$

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

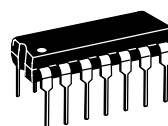
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



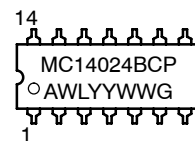
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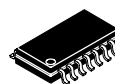
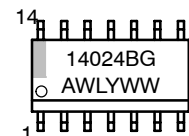
### MARKING DIAGRAMS



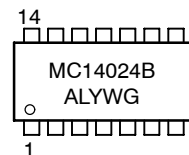
PDIP-14  
P SUFFIX  
CASE 646



SOIC-14  
D SUFFIX  
CASE 751A



SOEIAJ-14  
F SUFFIX  
CASE 965



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

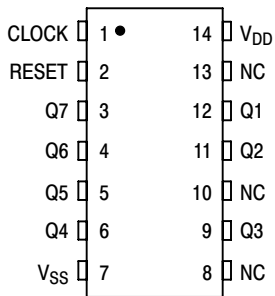
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# MC14024B

## TRUTH TABLE

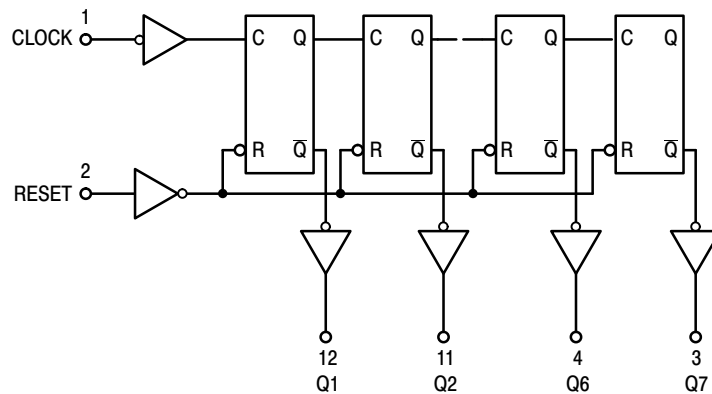
Clock	Reset	State
0	0	No Change
0	1	All Outputs Low
1	0	No Change
1	1	All Outputs Low
↗	0	No Change
↗	1	All Outputs Low
↘	0	Advance One Count
↘	1	All Outputs Low

## PIN ASSIGNMENT



V<sub>DD</sub> = PIN 14  
V<sub>SS</sub> = PIN 7  
NC = NO CONNECTION

## LOGIC DIAGRAM



Q3 = PIN 9  
Q4 = PIN 6  
Q5 = PIN 5

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC14024BCP	PDIP-14	25 Units / Rail
MC14024BCPG	PDIP-14 (Pb-Free)	
MC14024BD	SOIC-14	55 Units / Rail
MC14024BDG	SOIC-14 (Pb-Free)	
MC14024BDR2	SOIC-14	2500 / Tape & Reel
MC14024BDR2G	SOIC-14 (Pb-Free)	
MC14024BFEL	SOEIAJ-14	2000 / Tape & Reel
MC14024BFELG	SOEIAJ-14 (Pb-Free)	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MC14024B

## ELECTRICAL CHARACTERISTICS (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	- 55° C		25° C			125° C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level V <sub>OL</sub>	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
15		-	0.05	-	0	0.05	-	0.05		
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level V <sub>OH</sub>	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
		10	9.95	-	9.95	10	-	9.95	-	
		15	14.95	-	14.95	15	-	14.95	-	
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level V <sub>IL</sub>	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
		10	-	3.0	-	4.50	3.0	-	3.0	
15		-	4.0	-	6.75	4.0	-	4.0		
(V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	"1" Level V <sub>IH</sub>	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
		10	7.0	-	7.0	5.50	-	7.0	-	
		15	11	-	11	8.25	-	11	-	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source I <sub>OH</sub>	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
10		-1.6	-	-1.3	-2.25	-	-0.9	-		
15		-4.2	-	-3.4	-8.8	-	-2.4	-		
(V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Sink I <sub>OL</sub>	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
		10	1.6	-	1.3	2.25	-	0.9	-	
		15	4.2	-	3.4	8.8	-	2.4	-	
Input Current	I <sub>in</sub>	15	-	± 0.1	-	± 0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0	-	5.0	-	0.005	5.0	-	150	μAdc
		10	-	10	-	0.010	10	-	300	
		15	-	20	-	0.015	20	-	600	
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	I <sub>T</sub>	5.0 10 15	$I_T = (0.31 \mu\text{A/kHz}) f + I_{DD}$ $I_T = (0.60 \mu\text{A/kHz}) f + I_{DD}$ $I_T = (1.89 \mu\text{A/kHz}) f + I_{DD}$							μAdc

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25° C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.001.

# MC14024B

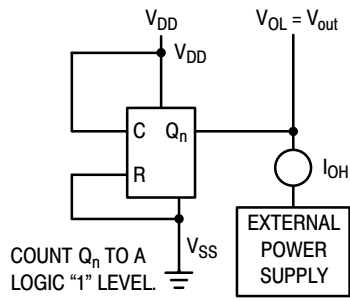
## SWITCHING CHARACTERISTICS (Note 5) ( $C_L = 50 \text{ pF}$ , $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TLH},$ $t_{THL}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1 $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 295 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 117 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 85 \text{ ns}$ Clock to Q7 $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 915 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 367 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 275 \text{ ns}$ Reset to $Q_n$ $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 415 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 217 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 155 \text{ ns}$	$t_{PLH},$ $t_{PHL}$	5.0 10 15  5.0 10 15  5.0 10 15	– – –  – – –  – – –	380 150 110  1000 400 300  500 250 180	600 230 175  2000 750 565  800 400 300	ns
Clock Pulse Width	$t_{WH}$	5.0 10 15	500 165 125	200 60 40	– – –	ns
Reset Pulse Width	$t_{WH}$	5.0 10 15	600 350 260	375 200 150	– – –	ns
Reset Removal Time	$t_{rem}$	5.0 10 15	625 190 145	250 75 50	– – –	ns
Clock Input Rise and Fall Time	$t_{TLH}, t_{THL}$	5.0 10 15	– – –	– – –	1.0 8.0 200	s ms $\mu\text{s}$
Input Pulse Frequency	$f_{cl}$	5.0 10 15	– – –	2.5 8.0 12	1.0 3.0 4.0	MHz

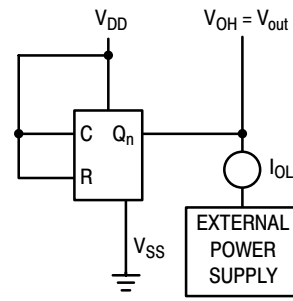
5. The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

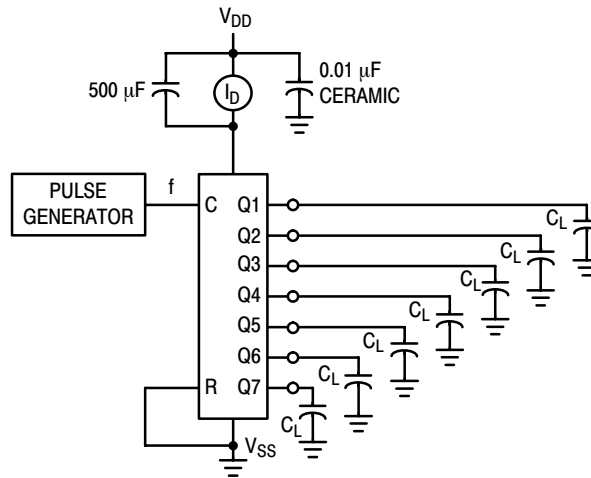
# MC14024B



**Figure 1. Typical Output Source Characteristics Test Circuit**

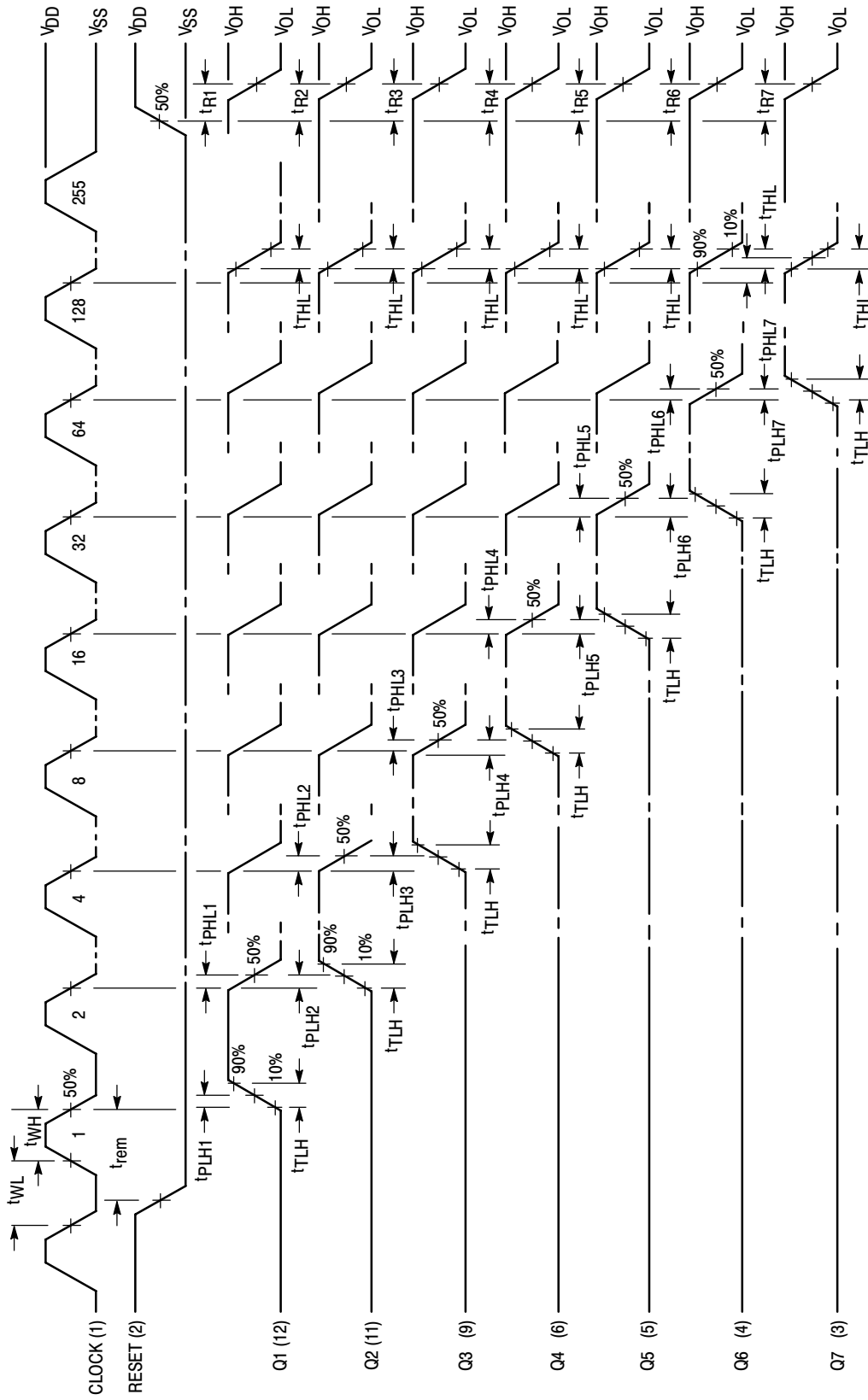


**Figure 2. Typical Output Sink Characteristics Test Circuit**



**Figure 3. Power Dissipation Test Circuit**

MC14024B



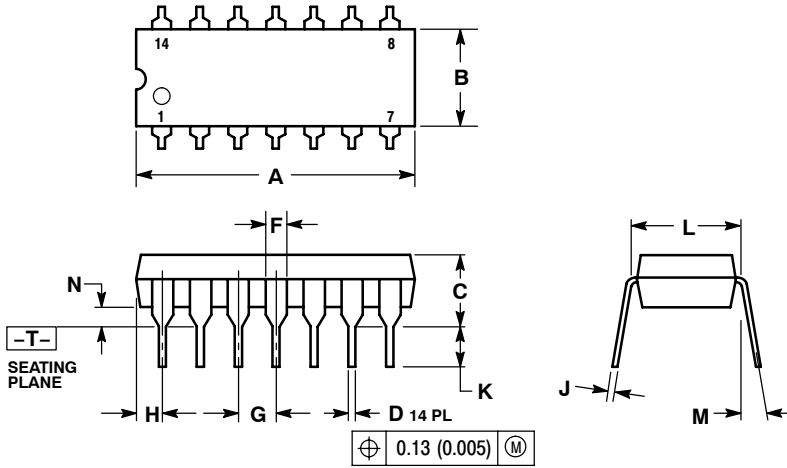
Input  $t_{TLH}$  and  $t_{THL} = 20$  ns

Figure 4. Functional Waveforms

# MC14024B

## PACKAGE DIMENSIONS

**PDIP-14**  
CASE 646-06  
ISSUE P



**NOTES:**

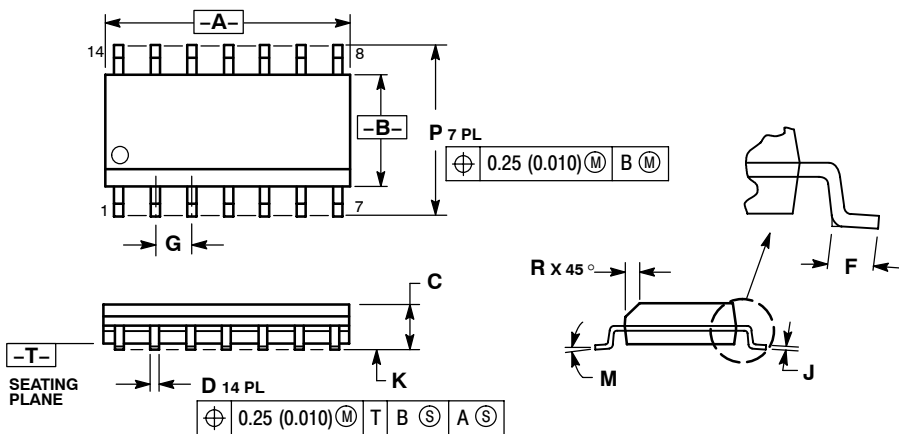
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

# MC14024B

## PACKAGE DIMENSIONS

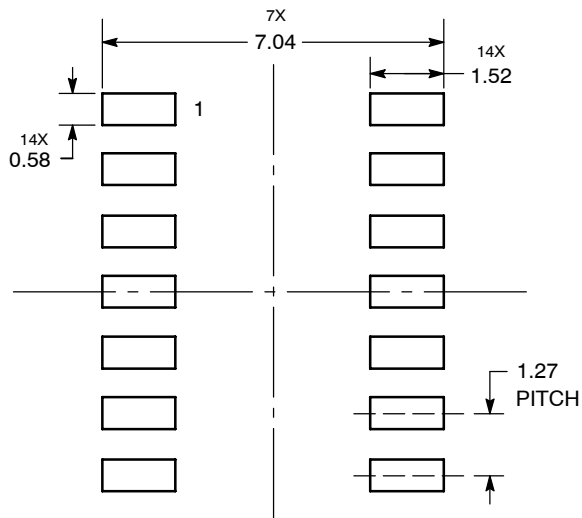
SOIC-14  
CASE 751A-03  
ISSUE H



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



# MC14024B

## PACKAGE DIMENSIONS

SOEIAJ-14  
CASE 965-01  
ISSUE A



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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